

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







Foil-Format Grease Replacement for Maximum Heat Transfer

Features and Benefits

- · Thermal impedance: 0.22°C-in2/W (@50 psi)
- · Maximum heat transfer
- · Aluminum foil coated both sides
- · Designed to replace thermal grease



Q-Pad II is a composite of aluminum foil coated on both sides with thermally / electrically conductive Sil-Pad rubber. The material is designed for those applications in which maximum heat transfer is needed and electrical isolation is not required. Q -Pad II is the ideal thermal interface material to replace messy thermal grease compounds.

Q-Pad II eliminates problems associated with grease such as contamination of reflow solder or cleaning operations. Unlike grease, Q-Pad II can be used prior to these operations Q-Pad II also eliminates dust collection which can cause possible surface shorting or heat buildup.

TYPICAL P	ROPER	TIES O	F Q-P	AD II		
PRO PERT Y	IMPERIAL VALUE		METRIC VALUE		TEST METHOD	
Color	Black		Black		Visual	
Reinforcement Carrier	Aluminum		Aluminum		_	
Thickness (inch) / (mm)	0.006		0.152		ASTM D374	
Hardness (Shore A)	93		93		ASTM D2240	
Continuous Use Temp (°F) / (°C)	-76 to 356		-60 to 180		_	
ELECTRICAL						
Dielectric Breakdown Voltage (Vac)	N on-Insulating		N on-Insulating		ASTM D149	
Dielectric Constant (1000 Hz)	NA		N A		ASTM D150	
Volume Resistivity (O hm-meter)	10²		10²		ASTM D257	
Flame Rating	V-O		V-O		U.L.94	
THERMAL						
Thermal Conductivity (W /m-K)	2.5		2.5		ASTM D5470	
THERMAL PERFORMANCE vs PRESS	URE					
Pressure (psi)		10	25	50	100	200
TO -220 Thermal Performance (°C/W)		2.44	1.73	1.23	1.05	0.92
Thermal Impedance (°C-in²/W) (1)		0.52	0.30	0.22	0.15	0.12

Typical Applications Include:

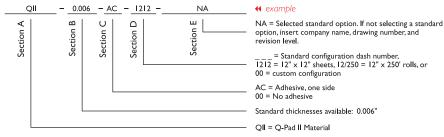
- · Between a transistor and a heat sink
- · Between two large surfaces such as an L-bracket and the chassis of an assembly
- · Between a heat sink and a chassis
- · Under electrically isolated power modules or devices such as resistors, transformers and solid state relays

Configurations Available:

- · Sheet form, die-cut parts and roll form
- · W ith or without pressure sensitive adhesive

Building a Part Number

Standard Options



Note: To build a part number, visit our website at www.bergquistcompany.com.

Sil-Pad®: U.S. Patents 4,574,879; 4,602,125; 4,602,678; 4,685,987; 4,842,911 and others